

HEAT SINK ASSEMBLY

Abstract of the Disclosure

The invention provides a heat sink assembly, and a method of making and using a heat sink assembly, for cooling a device using circulating fluid. The heat sink assembly comprises a housing including at least one housing inlet passage and at least one housing outlet passage. A first cavity is disposed in the housing and a plurality of first cavity column members are disposed in the first cavity. The first cavity column members are arranged in a plurality of rows such that first cavity column members in a row are staggered with respect to first cavity column members in an adjacent row. The heat sink assembly further includes a second cavity disposed in the housing and a plurality of second cavity column members disposed in the second cavity. The second cavity column members are arranged in a plurality of rows, which are also staggered.

Figures

[illegible]